# muRata

**Reference Specification** 

DEF Series/6.3kVp-p Lead Type Disc Ceramic Capacitors for LCD Backlight Inverter Circuit only

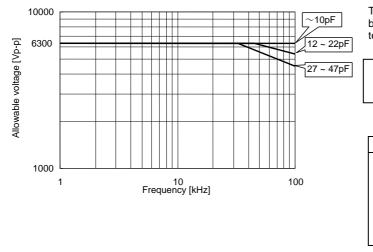
Product specifications in this catalog are as of Dec. 2017, and are subject to change or obsolescence without notice.

Please consult the approval sheet before ordering.Please read rating and Cautions first.

## 

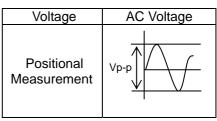
## 1. OPERATING VOLTAGE

The frequency of the applied sine wave voltage should be less than 100kHz. The applied voltage should be less than the value shown in following figure. In case of non-sine wave which include a harmonic frequency, please contact our sales representatives or product engineers.



The temperature of the surface of capacitor: below the upper limit of its rated operating temperature range (including self-heating.)

The capacitors can be applied maximum 6.3kVp-p at 100kHz when lamps turn on.



### 2. OPERATING TEMPERATURE AND SELF-GENERATED HEAT

Keep the surface temperature of a capacitor below the upper limit of its rated operating temperature range.

Be sure to take into account the heat generated by the capacitor itself. When the capacitor is used in a high-frequency current, pulse current or similar current, it may self-generate heat due to dielectric loss. Excessive heat may lead to deterioration of the capacitor's characteristics and reliability. (Never attempt to perform measurement with the cooling fan running. Otherwise, accurate measurement cannot be ensured.)

#### 3. FAIL-SAFE

When capacitor would be broken, failure may result in a short circuit. Be sure to provide an appropriate fail-safe function like a fuse on your product if failure would follow an electric shock, fire or fume.

#### 4. VIBRATION AND IMPACT

Do not expose a capacitor or its leads to excessive shock or vibration during use.

#### 5. SOLDERING

When soldering this product to a PCB/PWB, do not exceed the solder heat resistance specification of the capacitor. Subjecting this product to excessive heating could melt the internal junction solder and may result in thermal shocks that can crack the ceramic element.

When soldering capacitor with a soldering iron, it should be performed in following conditions.

Temperature of Iron chip	: 400 °C max.
Soldering iron wattage	: 50 W max.
Soldering time	: 3.5 s max.

#### 6. BONDING, RESIN MOLDING AND COATING

In case of bonding, molding or coating this product, verify that these processes do not affect the quality of capacitor by testing the performance of the bonded, molded or coated product in the intended equipment.

In case of the amount of applications, dryness / hardening conditions of adhesives and molding resins containing organic solvents (ethyl acetate, methyl ethyl ketone, toluene, etc.) are unsuitable, the outer coating resin of a capacitor is damaged by the organic solvents and it may result, worst case, in a short circuit.

The variation in thickness of adhesive, molding resin or coating may cause a outer coating resin cracking and/or ceramic element cracking of a capacitor in a temperature cycling.

#### 7. TREATMENT AFTER BONDING, RESIN MOLDING AND COATING

When the outer coating is hot (over 100  $^{\circ}$ C) after soldering, it becomes soft and fragile. So please be careful not to give it mechanical stress.

Failure to follow the above cautions may result, worst case, in a short circuit and cause fuming or partial dispersion when the product is used.

#### 8. OPERATING AND STORAGE ENVIRONMENT

The insulating coating of capacitors does not form a perfect seal; therefore, do not use or store capacitors in a corrosive atmosphere, especially where chloride gas, sulfide gas, acid, alkali, salt or the like are present. And avoid exposure to moisture. Before cleaning, bonding, or molding this product, verify that these processes do not affect product quality by testing the performance of a cleaned, bonded or molded product in the intended equipment. Store the capacitors where the temperature and relative humidity do not exceed -10 to 40 °C and 15 to 85%. Use capacitors within 6 months after delivered. Check the solderability after 6 months or more.

#### 9. LIMITATION OF APPLICATIONS

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects which might directly cause damage to the third party's life, body or property.

- 1. Aircraft equipment
- 2. Aerospace equipment
- 3. Undersea equipment
- 4. Power plant control equipment
- 5. Medical equipment
- 6. Transportation equipment (vehicles, trains, ships, etc.)
- 7. Traffic signal equipment
- 8. Disaster prevention / crime prevention equipment
- 9. Data-processing equipment exerting influence on public
- 10. Application of similar complexity and/or reliability requirements to the applications listed in the above.

#### NOTICE

#### 1. CLEANING (ULTRASONIC CLEANING)

To perform ultrasonic cleaning, observe the following conditions. Rinse bath capacity: Output of 20 watts per liter or less. Rinsing time: 5 min maximum.

Do not vibrate the PCB/PWB directly.

Excessive ultrasonic cleaning may lead to fatigue destruction of the lead wires.

#### 2. CAPACITANCE CHANGE OF CAPACITORS

Capacitance might change a little depending on a surrounding temperature or an applied voltage. Please contact us if you use for the strict time constant circuit.

## 

- 1. Please make sure that your product has been evaluated in view of your specifications with our product
- being mounted to your product. 2.You are requested not to use our product deviating from this specification.

#### 1. Application

This specification is applied to Lead Type Disc Ceramic Capacitors DEF series used for LCD Backlight Inverter Circuit only.

Please contact us when using this product for any other applications than described in the above. Do not use these products in any automotive power train or safety equipment including battery chargers for electric vehicles and plug-in hybrids.

#### 2. Rating

2-1. Operating temperature range

-25 ~ +105°C

2-2. Part number configuration

ex.) <u>DEF</u>	2C	LH	100	J	A3	В	
Series	Temperature	Rated	Capacitance	Capacitance	Lead	Packing	Individual
	characteristic	voltage		tolerance	code	style code	specification

• Temperature characteristic

Code	Temperature characteristic
2C	СН
1X	SL

Please confirm detailed specification on [ Specification and test methods ].

#### • Rated voltage

Code	Rated voltage			
LH	6.3kVp-p			

Please confirm detailed specification on [ OPERATING VOLTAGE ].

#### • Capacitance

The first two digits denote significant figures ; the last digit denotes the multiplier of 10 in pF. ex.) In case of 100.

$$10 \times 10^{\circ} = 10 \text{pF}$$

Capacitance tolerance

Please refer to [ Part number list ].

• Lead code

Code	Lead style
A*	Vertical crimp long type
J*	Vertical crimp short type
N*	Vertical crimp taping type

\* Please refer to [ Part number list ].

Solder coated copper wire is applied for termination.

#### • Packing style code

Code	Packing type
В	Bulk type
A	Ammo pack taping type

Individual specification

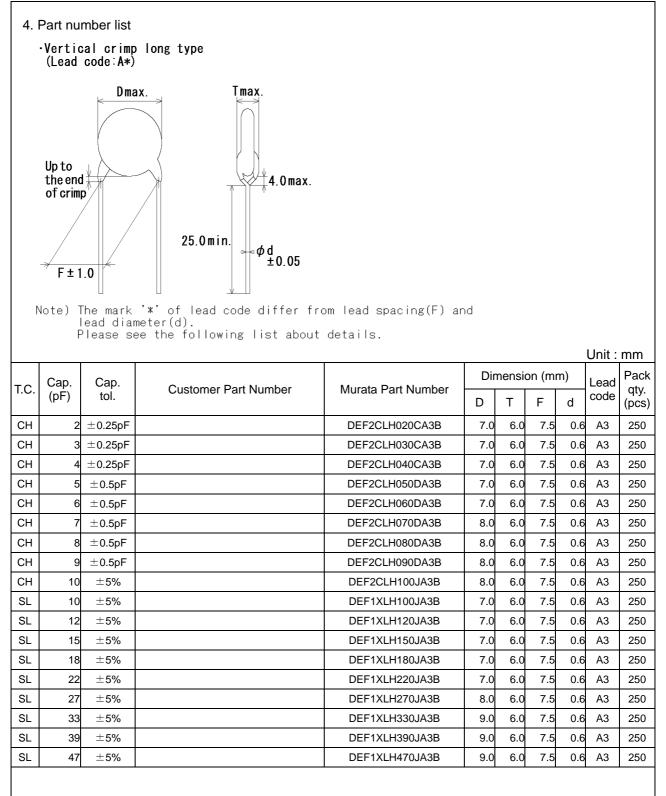
In case part number cannot be identified without 'individual specification', it is added at the end of part number.

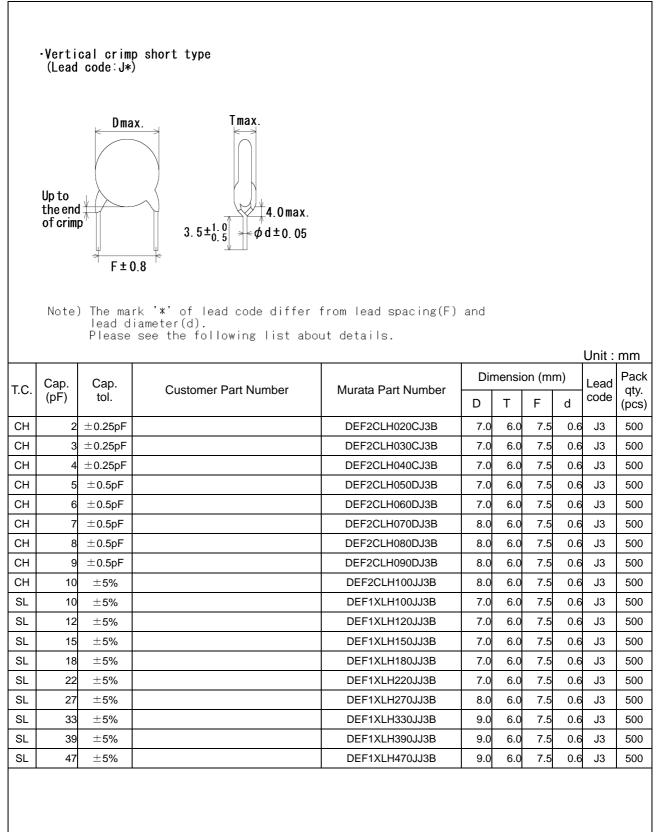
## 3. Marking

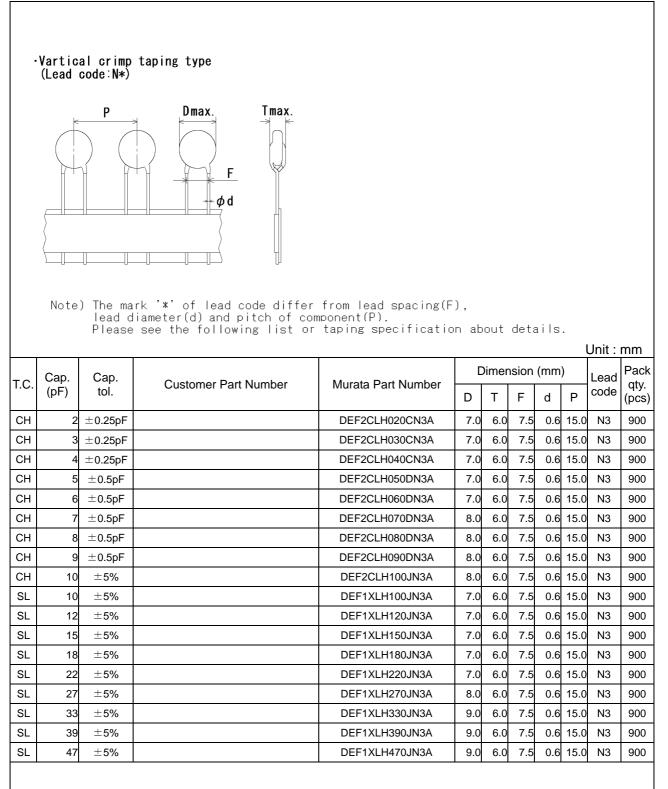
Temperature characterist Nominal capacitance Capacitance tolerance	ic : Upper horizontal line for : Actual value : Code	char. CH(Omitted for char. SL)
Rated voltage	: Letter code(Marked with	6K~)
Manufacturing year	: Letter code(The last digi	t of A.D. year.)
Manufacturing month	: Code	
	( Feb./Mar. → 2	Aug./Sep. → 8
	Apr./May → 4	Oct./Nov. → O
	$\int Jun./Jul. \rightarrow 6$	Dec./Jan. → D )

(Example)

10J 6K~ **0**D





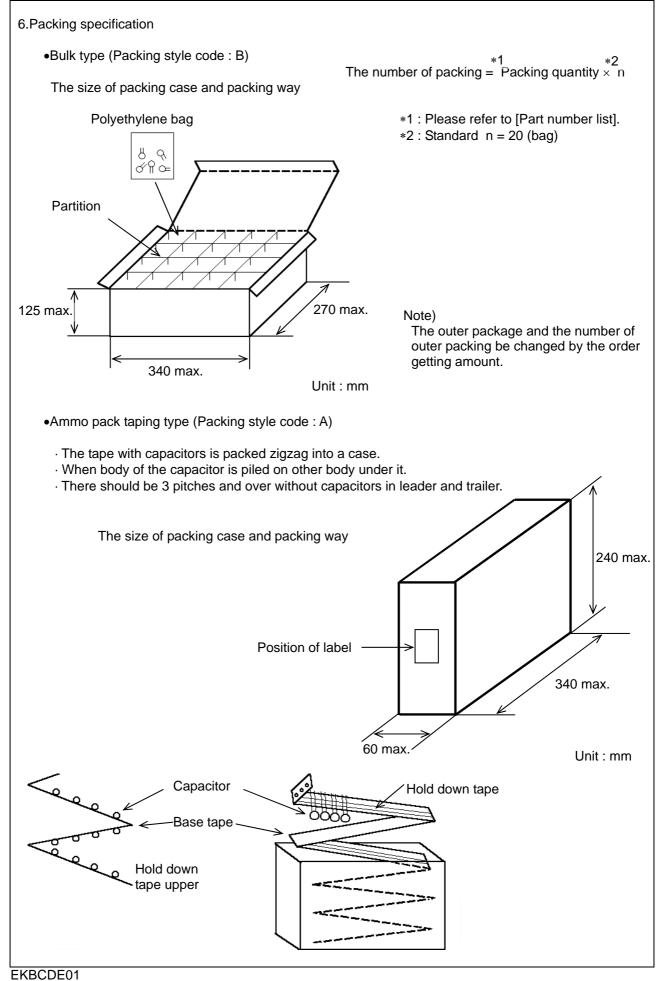


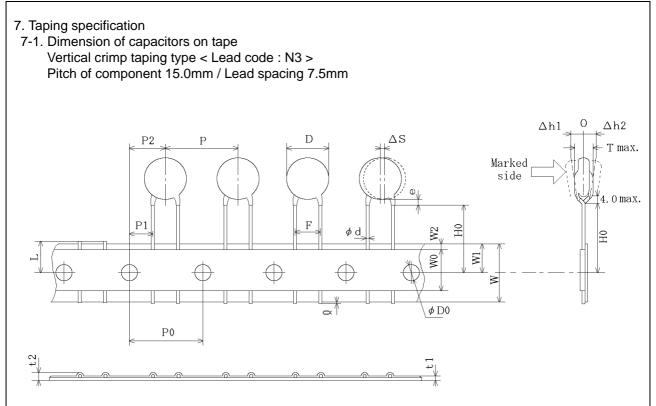
### **Reference only**

No. 1	ecification and test			nonification			Tool	mothod			
	Ite Appearance and o			pecification defect on appear	ance	Test method The capacitor should be inspected by naked eyes					
	, ppourance and (		form and dir			for visible evidence of defect.					
				r to [Part number	list].	Dimensions should be measured with slide calipers.					
2	Marking		To be easily			The capacitor should be inspected by naked eyes.					
3	Dielectric	Between lead	No failure.			The capacitor should not be damaged when					
	strength	trength wires				DC12.6kV applied between the lead wires for					
					1 to 5 s.						
	De du		(Charge/Disc			1					
		Body	No failure.			The capacitor					
insulation			balls of diameter 1mm so that shortcircuited, is kept about					lead wire	,		
					off the balls a						
						and DC volta			V		
					applied for 1 to 5 s between						
					capacitor lead wires and				About 2r		
					small metals.		000	20000000木	NOUL 21		
						(Charge/Disc				al balls	
4	Insulation	Between lead	10000MΩ n	nin.		The insulation				d with	
-	Resistance (I.R.)	wires		field to low on a s		DC500±50V					
5	Capacitance		within spec	ified tolerance.		The capacita			ed at 20°C	; with	
6	0		400.000*2	nin. (30pF under)		1±0.2MHz a	,	,		01.41.1	
6	Q		400+20C^2n 1000 min.	nin. (30pF under) (30pF min.)	)	The Q should		rea at 20°C	, with $1\pm0$ .	∠iviHz	
7	Temperature char	acteristic		(30pr mm.) )±60ppm/°C		and AC5V(r.n The capacita		rement sho	uld he ma	de at	
'	iomporatore orial			350 to - 1 000ppi	m/°C	each step spe			aia bo ilid	ac ai	
				ige: +20 to 85°C)							
			(Temp. Tan	ige. +20 to 05 C)		I				_	
			Step 1			2	3	4	5		
				Temp.(°C)	20±	2 -25±3	20±2	85±2	20±2		
0	Other with a file stat		L a s d a dra a	handel and such a ff			C	Latalat Cont		_	
8	Strength of lead	Pull		hould not cut off.	As shown in t				II.H.J.		
			Capacitor should not be broken.			of the capacitor and apply a tensile weight gradually to each lead wire in the radial					
						direction of the capacitor up to 10N w					
						and keep it for 10±1 s.					
		Bending				Each lead wire should be subjected to 5N of weight					
						and bent 90° at the point of egress, in one direction,					
						then returned to its original position and bent 90° in					
						the opposite	direction at	the rate of	one bend	in 2 to	
9	Vibration	Appearance	No marked	defect.		3 s. The capacitor	should be	firmly sold	ered to the	,	
Ũ	resistance	Capacitance		ified tolerance.		supporting lea					
		Q		nin. (30pF under)	)	range of 10 to					
			1000 min.	(30pF min.)		about a 1min rate of vibration change from 10Hz to 55Hz and back to 10Hz. Apply for a total of 6 h;					
10	Colders hills (1	- 4-	Lacit	haved by a state	-J	2 h each in 3					
10	Solderability of lea	aas		hould be soldered		The lead wire					
			with uniformly coated on the axial direction over 3/4 of the			ethanol solution of $25wt\%$ rosin and then into molten solder for $2\pm0.5$ s. In both cases the depth c					
				tial direction.		dipping is up					
						lead wires.		5 to 2.000			
						Temp. of solder :					
								245±5°C Lead Free Solder (Sn-3Ag-0.5Cu)			
						245±5°C L 235±5°C H			BAg-0.5Cu	)	

#### **Reference only**

			Reference only	1			
No.	lte		Specification			t method	
11	Soldering effect (Non-preheat)	Appearance Capacitance	No marked defect. Within ± 2.5%		ad wire should be of 350±10°C up t		
		change			in body for 3.5±0		
		Dielectric strength (Between	Per item 3.	Post-tr	eatment : Capac 2 h at *	itor should be froom condit	
12	Soldering effect	lead wires) Appearance	No marked defect.	First th	e capacitor shou	ld be stored	at 120+0/-5°C
12	(On-preheat)	Capacitance	Within ± 2.5%	for 60+			at 120+0/-5 C
	(	change Dielectric	Per item 3.	Then, a immers	as in figure, the le sed solder of 260	+0/-5°C up t	o 1.5 to 2.0mn
		strength (Between lead wires)		from th	Thermal insulating	Capacitor	r Omm
				Post-tr	eatment : Capaci	itor should b	er
					2 h at *	<sup>1</sup> room condit	tion.
13	Humidity	Appearance	No marked defect.		capacitor for 50		t 40±2°C in 90
	(Under steady state)	Capacitance change	Within $\pm$ 5%		eatment : Capac		o stored for 1 +
	State)	Q	200+10C* <sup>2</sup> min. (10pF under)	Post-tr		<sup>1</sup> room condi	
		<u> </u>	275+5/2C*2min.				
			(10pF min. and 30pF under)				
		I.R.	350 min. (30pF min.) 1 000MΩ min.	_			
14	Life	Appearance	No marked defect.		6.3kVp-p at the fr		
		Capacitance	Within ± 3%		-48/-0 h at 105±2 6 max (Charge		
		change Q	200+10C*2min. (10pF under)	<pre>of 50% </pre>		a Discharge (	Junent⊵oumA.
		G.	275+5/2C*2min.	I —	apacitance(pF)	Frequency(	kHz)
			(10pF min. and 30pF under) 350 min. (30pF min.)		~10	100	((12)
		I.R.	$2000M\Omega$ min. (30)P min.)	-	-		
					12~22	45	
					27~47	33	
						<sup>1</sup> room condit	tion.
15	Temperature	Appearance	No marked defect.		pacitor should be		
	and Immersion cycle	Capacitance change	Within ± 3%	-	then consecutiv		ersion cycles.
		Q	200+10C* <sup>2</sup> min. (10pF under)		erature cycle>		~~ ]
			275+5/2C*2min. (10pF min. and 30pF under)	Ste 1	p Temperature -25±3	e(°C) Tir 30	
			350 min. (30pF min.)	2	Room Ten		
		I.R.	2000MΩ min.	3	+105±3	30	min
		Dielectric strength	Per item 3.	4	Room Ten	np. 3 r	nin
		(Between lead wires)		<imme< td=""><td>rsion cycle&gt;</td><td>Cycle ti</td><td>me : 5 cycle</td></imme<>	rsion cycle>	Cycle ti	me : 5 cycle
		,		Step	Temperature(°C	C) Time	Immersion water
				1	+65+5/-0	15 min	Clean water
				2	0±3	15 min	Salt water
						Cycle ti	me : 2 cycle
						*1room cond	
	om condition" Temp ' expresses nomina		°C, Relative humidity: 45 to 75%, Atm ue (pF)	ospheric	pressure: 86 to 2	106kPa	

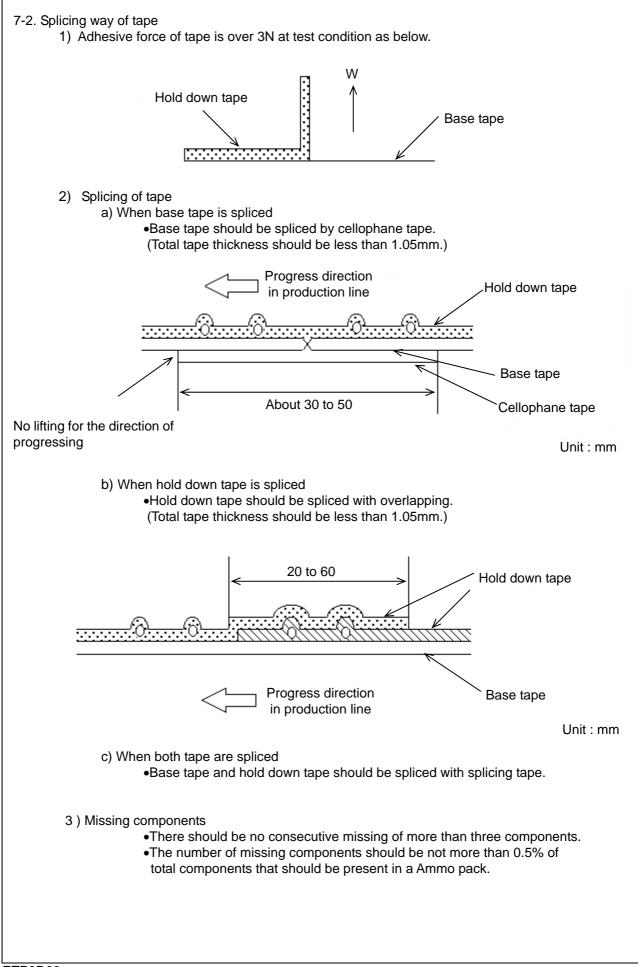




Unit : mm

		Unit : mm			
Code	Dimensions	Remarks			
Р	15.0±2.0				
P0	15.0±0.3				
F	7.5±1.0				
P2	7.5±1.5	Deviation of programs direction			
P1	3.75±1.0	Deviation of progress direction			
D	Please refer to [	Part number list ].			
ΔS	0±2.0	They include deviation by lead bend .			
W	18.0±0.5				
W1	9.0±0.5	Deviation of tape width direction			
	40.0120				
	18.0±0~				
Q	+0.5~-1.0				
φD0	4.0±0.1				
φd	0.60±0.05				
t1	0.6±0.3				
t2	1.5 max.	They include hold down tape thickness.			
∆h1	2.0 mov				
∆h2					
L	<b>11.0</b> ± <sup>0</sup> <sub>1.0</sub>				
WO	11.5 min.				
W2	1.5±1.5				
е	Up to the end of crimp				
Т	Please refer to [	Part number list ].			
· · · · · · · · · · · · · · · · · · ·	P         P0         F         P2         P1         D         ΔS         W         W1         H0         Q         φD0         φd         t1         t2         Δh1         Δh2         L         W0         W2         e	P         15.0±2.0           P0         15.0±0.3           F         7.5±1.0           P2         7.5±1.5           P1         3.75±1.0           D         Please refer to [           ΔS         0±2.0           W         18.0±0.5           W1         9.0±0.5           H0         18.0± $_0^{2.0}$ Q         +0.5~-1.0           φD0         4.0±0.1           φd         0.60±0.05           t1         0.6±0.3           t2         1.5 max.           Δh1         2.0 max.           L         11.0± $_{1.0}^{1.0}$ W0         11.5 min.           W2         1.5±1.5         e           Up to the end of			

ETP1N302A



This products of the following crresponds to EU RoHS 当製品は以下の欧州RoHSに対応しています。

(1) RoHS

EU RoHs 2011/65/EC compliance 2011/65/EC(改正RoHS指令)に対応

maximum concentration values tolerated by weight in homogeneous materials

1000 ppm maximum Lead

1000 ppm maximum Mercury

•100 ppm maximum Cadmium

•1000 ppm maximum Hexavalent chromium

•1000 ppm maximum Polybrominated biphenyls (PBB)

•1000 ppm maximum Polybrominated diphenyl ethers (PBDE)